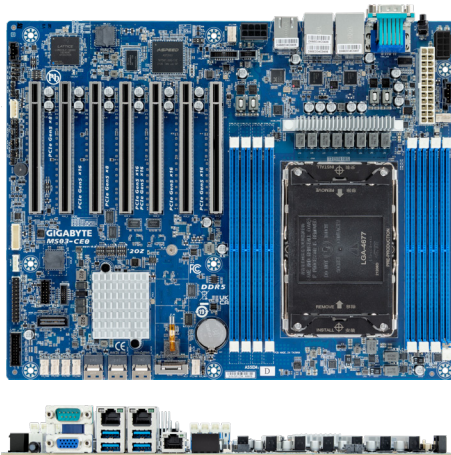


MS03-CEO

4th Gen Intel Xeon Scalable UP Motherboard



Features

- 4th Gen Intel® Xeon® Scalable Processors
- Intel® Xeon® CPU Max Series
- Single processor, LGA4677
- 8-Channel RDIMM DDR5, 8 x DIMMs
- Supports Intel® Optane™ Persistent Memory 300 series
- Intel® C741 Chipset
- 2 x 1Gb/s LAN ports (Intel® I210-AT)
- 1 x Dedicated management port
- 3 x SlimSAS with 12 x SATA 6Gb/s ports
- 1 x Ultra-Fast M.2 with PCIe Gen3 x4 interface
- 7 x PCIe Gen5 x16 or x8 expansion slots

Specification

Form Factor	ATX (304.8W x 244D mm)	Internal I/O	1 x CPU fan header, 5 x System fan headers, 1 x USB 3.2 Gen1 header, 1 x TPM header, 1 x Front panel header, 1 x HDD back plane board header, 1 x PMBus connector, 1 x IPMB connector, 1 x Clear CMOS jumper, 1 x BIOS recovery jumper, 1 x Buzzer
CPU	4th Generation Intel® Xeon® Scalable Processors Intel® Xeon® CPU Max Series Intel® Xeon® Platinum Processor, Intel® Xeon® Gold Processor, Intel® Xeon® Silver Processor CPU TDP up to 350W	TPM	1 x TPM header with SPI interface Optional TPM2.0 kit: CTM010
Socket	1 x LGA 4677 (Socket E)	OS Compatibility	Windows Server 2019 / 2011 RHEL 8.4 / 8.5 / 8.6 / 8.7 / 9.0 / 9.1 (x64) SLES 15 SP3 / 15 SP4 (x64) Ubuntu 22.04 LTS / 22.04.1 LTS (x64) VMware ESXi 7.0 Update 3i / 8.0
Chipset	Intel® C741 Chipset	Board Management	Aspeed® AST2600 management controller GIGABYTE Management Console (AMI MegaRAC SP-X)
Memory	8-Channel DDR5 memory, 8 x DIMM slots RDIMM modules up to 128GB supported 3DS RDIMM modules up to 256GB supported Memory speed: Up to 4800 MHz	PSU Connectors	1 x 24-pin ATX main power connector 2 x 8-pin ATX 12V power connectors
LAN	2 x 1Gb/s LAN ports (Intel® I210-AT) 1 x I210 with NCSI function supported 1 x 10/100/1000 management LAN	Operating Properties	Operating temperature: 10°C to 40°C Operating humidity: 8-80% (non-condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20%-95% (non-condensing)
Video	Integrated in Aspeed® AST2600 2D Video Graphic Adapter with PCIe bus interface 1920x1200@60Hz 32bpp, DDR4 SDRAM	Retail Packaging Content	1 x MS03-CEO, 1 x I/O shield, 1 x Quick start guide, 3 x Carrier clips, 1 x SlimSAS for 4 x SATAIII cable Single Box dimensions: 360 x 330 x 80 mm Carton dimension: 674 x 424 x 385 mm Quantity: 10 x single box with one carton
SATA	3 x SlimSAS with 12 x SATA 6Gb/s ports	Bulk Packaging Content	10 x MS03-CEO, 10 x I/O shields, 30 x Carrier clips Carton dimensions: 600 x 473 x 495 mm
RAID	Intel® SATA RAID 0/1/10/5	Reference Numbers	Retail: 9MS03CEO0MR-000 Bulk: 9MS03CEO0NR-000 - I/O shield: 12AIO-MS03CE-00R
Expansion Slots	3 x PCIe x16 (Gen5 x16) slots 2 x PCIe x16 (Gen5 x16 or x8) slots 2 x PCIe x16 (Gen5 x8) slots 1 x M.2 slot - M-key, PCIe Gen3 x4, supports 2280 cards		
Rear I/O	4 x USB 3.2 Gen1, 1 x VGA, 1 x COM, 2 x RJ45, 1 x MLAN, 1 x ID button with LED		



Learn more about GIGABYTE server solutions, visit www.gigabyte.com/Enterprise

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